## DECLARATION OF INVENTORSHIP AND POWER OF ATTORNEY

## FOR PATENT APPLICATION

			Docket No.
As a be	low named inventor, I hereby dec	lare that:	<u>-</u>
My resi	dence, post office address and cit	izenship are as stated below next	to my name.
(if plur: entitled	al names are listed below) of the s	ubject matter which is claimed an	ed below) or an original, first and joint inventor ad for which a patent is sought on the invention FABRICATING OF SEMICONDUCTOR  PACKAGE.
(check	one) 🛛 is attached hereto.		
÷	was filed on		
			(if applicable).
as ame	nded by any amendment referred	to above.	material to Patentability as defined in 37 CFR
fisted b	y claim foreign priority benefits un elow and have also identified belo that of the application on which p	w any foreign application for pat	application(s) for patent or inventor's certificate tent or inventor's certificate having a filing date
21 P	oreign Application(s)		
	APPLICATION NUMBER	COUNTRY	FILING DATE (Day/Month/Year)
	TW 90133149	TAIWAN, ROC	DECEMBER 31, 2001

I hereby claim the benefit under 35 USC § 120 of any United States application (s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed inn the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose to the Office information which is material to patentability as defined in CFR § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application

APPLICATION NUMBER

FILING DATE
(Day/Month/Year)

STATUS

(Patented, Pending, Abandoued)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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/XXX

Address all telephone calls

Address all correspondence to:

Mr. Peter F. Corless EDWARDS & ANGELL, LLP 101 Federal Street, Boston

MA 02110 U.S.A.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full name of sole or first inventor DAVII	TSENG _	
Inventor's signature Jan Seru	Date Nov. >9. >00/	
Residence FENG YUAN -	Citizenship TAIWAN, ROC	
Post Office Address 5F., No. 35, I	Lane 312, Yuan Huan East Road, Feng Yuan City, Taiwan ROC	
Full name of second joint inventor, if any	Chien-Ping HUANG  Ping Huang  Date  Citizenship TAIWAN ROC	
Post Office Address No. 8, Lane 26,	Kang Chuang Street, Chutung Chen, Hsinchu Hsien,	
Taiwan, ROC		
gamen .		
Jull name of third joint inventor, if any	Kun-Ming HUANG	
Third Inventor's signature Jour Ving	Date M. 29 mul  Citizenship TAIWAN ROC	
Residence Chang Hua (/	Citizenship TAIWAN ROC	
Post Office Address No. 29, Lane	13, Sec. 1, Chang-Ho Road, Chang Hua City, TAIWAN, ROC	
Ti		
	Date	
	Citizenship	
Post Office Address		
Full name of fifth joint inventor, if any		
Fifth Inventor's signature		
Residence		
Post Office Address		
Full name of sixth joint inventor, if any		
	Date	
	Citizenship	
Post Office Address		